

## **Description**

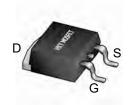
The IRFR2905ZPBF uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})}$ , low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



#### TO-252-2L

## **General Features**

 $V_{DS} = 60V I_{D} = 50 A$ 

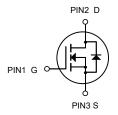
 $R_{DS(ON)}$  < 15m $\Omega$  @  $V_{GS}$ =10V

## **Application**

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
IRFR2905ZPBF	TO-252-2L	HXY MOSFET	2500

## Absolute Maximum Ratings (T<sub>C</sub>=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	in Current, V <sub>GS</sub> @ 10V <sup>1</sup> 25	
Ідм	Pulsed Drain Current <sup>2</sup>	90	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	39.2	mJ
las	Avalanche Current	28	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	45	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-Ambient <sup>1</sup>	62	°C/W
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	2.8	°C/W



# Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

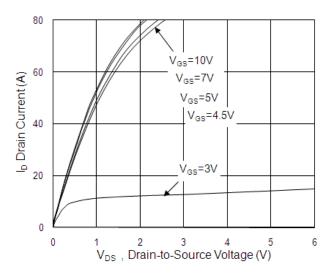
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVoss	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V
△BVdss/△TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.057		V/°C
		V <sub>GS</sub> =10V , I <sub>D</sub> =20A		11	15	
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		15	20	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.2		2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-5.68		mV/°C
		$V_{DS}$ =48V , $V_{GS}$ =0V , $T_{J}$ =25 $^{\circ}$ C			1	
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
Igss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =15A		45		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			19.3		
Qgs	Gate-Source Charge	V <sub>DS</sub> =48V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		7.1		nC
Q <sub>gd</sub>	Gate-Drain Charge			7.6		
T <sub>d(on)</sub>	Turn-On Delay Time			7.2		
Tr	Rise Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3 ,		50		
T <sub>d(off)</sub>	Turn-Off Delay Time	_R <sub>G</sub> -3.3 , _I <sub>D</sub> =15A		36.4		ns
Tf	Fall Time	-10-13A		7.6		
Ciss	Input Capacitance			2423		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		145		pF
Crss	Reverse Transfer Capacitance			97		
Is	Continuous Source Current <sup>1,5</sup>				35	Α
Іѕм	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			80	Α
VsD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =A , T <sub>J</sub> =25°C			1	V
t <sub>rr</sub>	Reverse Recovery Time	I=-45A - 41/44-400A/:		16.3		nS
Qrr	Reverse Recovery Charge	IF=15A , dI/dt=100A/μs , TJ=25°C		11		nC

## Note:

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=28A
- 4. The power dissipation is limited by  $150^{\circ}$ C junction temperature 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation



## **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

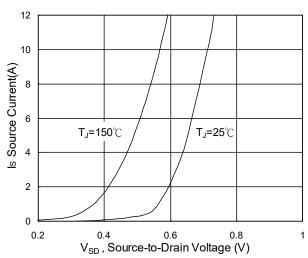


Fig.3 Forward Characteristics of Reverse

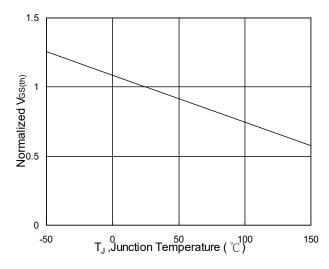


Fig.5 Normalized V<sub>GS(th)</sub> v.s T<sub>J</sub>

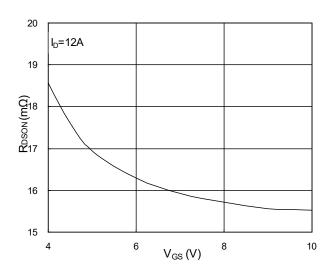


Fig.2 On-Resistance v.s Gate-Source

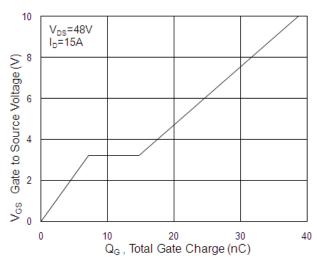


Fig.4 Gate-Charge Characteristics

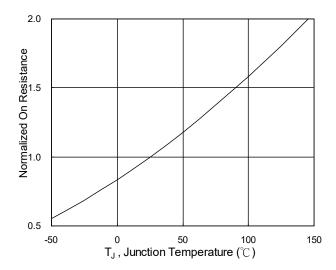
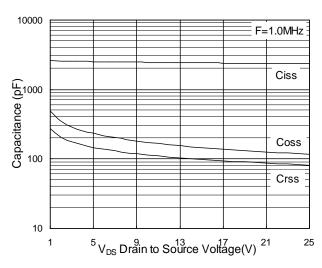


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>



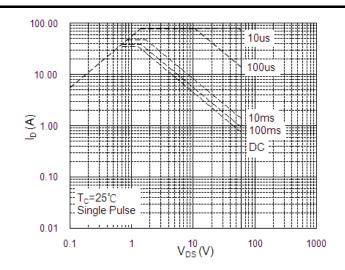


Fig.7 Capacitance

Fig.8 Safe Operating Area

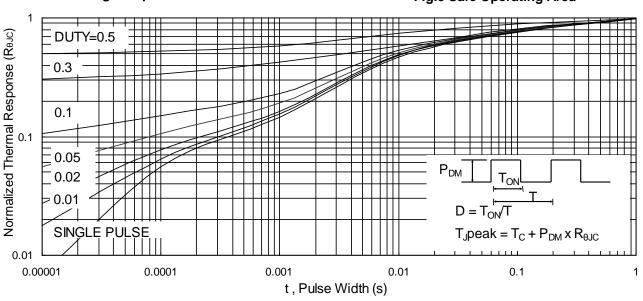


Fig.9 Normalized Maximum Transient Thermal Impedance

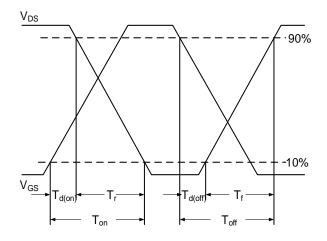


Fig.10 Switching Time Waveform

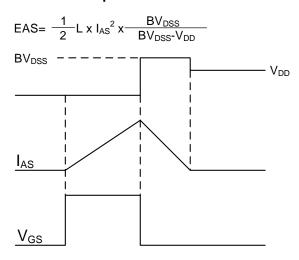
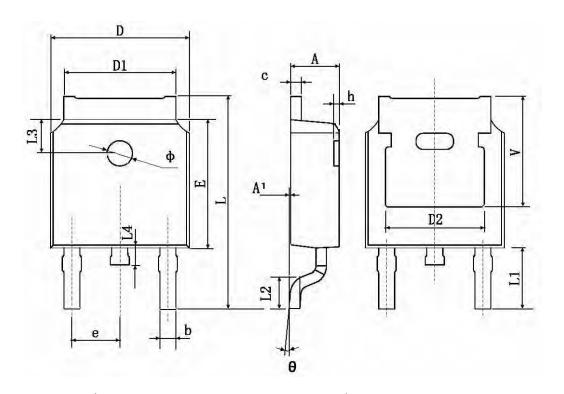


Fig.11 Unclamped Inductive Switching Waveform



# **TO-252-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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